

Semiconductor Advanced Packaging-United States Market Status and Trend Report 2013-2023

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Abstracts

Report Summary

Semiconductor Advanced Packaging-United States Market Status and Trend Report 2013-2023 offers a comprehensive analysis on Semiconductor Advanced Packaging industry, standing on the readers' perspective, delivering detailed market data and penetrating insights. No matter the client is industry insider, potential entrant or investor, the report will provides useful data and information. Key questions answered by this report include:

Whole United States and Regional Market Size of Semiconductor Advanced Packaging 2013-2017, and development forecast 2018-2023

Main market players of Semiconductor Advanced Packaging in United States, with company and product introduction, position in the Semiconductor Advanced Packaging market

Market status and development trend of Semiconductor Advanced Packaging by types and applications

Cost and profit status of Semiconductor Advanced Packaging, and marketing status

Market growth drivers and challenges

The report segments the United States Semiconductor Advanced Packaging market as:

United States Semiconductor Advanced Packaging Market: Regional Segment Analysis (Regional Consumption Volume, Consumption Volume, Revenue and Growth Rate 2013-2023):

New England

The Middle Atlantic

The Midwest

The West

The South

Southwest

United States Semiconductor Advanced Packaging Market: Product Type Segment Analysis (Consumption Volume, Average Price, Revenue, Market Share and Trend 2013-2023):

FO WLP

2.5D/3D

FI WLP

Flip Chip

United States Semiconductor Advanced Packaging Market: Application Segment Analysis (Consumption Volume and Market Share 2013-2023; Downstream Customers and Market Analysis)

CMOS image sensors

Wireless connectivity devices

Logic and memory devices

MEMS and sensors

Analog and mixed ICs

United States Semiconductor Advanced Packaging Market: Players Segment Analysis (Company and Product introduction, Semiconductor Advanced Packaging Sales Volume, Revenue, Price and Gross Margin):

Advanced Semiconductor Engineering

Amkor Technology

Samsung Semiconductor

TSMC

China Wafer Level CSP

ChipMOS TECHNOLOGIES

FlipChip International

HANA Micron

Interconnect Systems (Molex)

Jiangsu Changjiang Electronics Technology (JCET)

King Yuan Electronics
Tongfu Microelectronics
Nepes
Powertech Technology (PTI)
SIGNETICS
Tianshui Huatian
Ultratech
UTAC

In a word, the report provides detailed statistics and analysis on the state of the industry; and is a valuable source of guidance and direction for companies and individuals interested in the market.

Contents

CHAPTER 1 OVERVIEW OF SEMICONDUCTOR ADVANCED PACKAGING

- 1.1 Definition of Semiconductor Advanced Packaging in This Report
- 1.2 Commercial Types of Semiconductor Advanced Packaging
 - 1.2.1 FO WLP
 - 1.2.2 2.5D/3D
 - 1.2.3 FI WLP
 - 1.2.4 Flip Chip
- 1.3 Downstream Application of Semiconductor Advanced Packaging
 - 1.3.1 CMOS image sensors
 - 1.3.2 Wireless connectivity devices
 - 1.3.3 Logic and memory devices
 - 1.3.4 MEMS and sensors
 - 1.3.5 Analog and mixed ICs
- 1.4 Development History of Semiconductor Advanced Packaging
- 1.5 Market Status and Trend of Semiconductor Advanced Packaging 2013-2023
 - 1.5.1 United States Semiconductor Advanced Packaging Market Status and Trend 2013-2023
 - 1.5.2 Regional Semiconductor Advanced Packaging Market Status and Trend 2013-2023

CHAPTER 2 UNITED STATES MARKET STATUS AND FORECAST BY REGIONS

- 2.1 Market Status of Semiconductor Advanced Packaging in United States 2013-2017
- 2.2 Consumption Market of Semiconductor Advanced Packaging in United States by Regions
 - 2.2.1 Consumption Volume of Semiconductor Advanced Packaging in United States by Regions
 - 2.2.2 Revenue of Semiconductor Advanced Packaging in United States by Regions
- 2.3 Market Analysis of Semiconductor Advanced Packaging in United States by Regions
 - 2.3.1 Market Analysis of Semiconductor Advanced Packaging in New England 2013-2017
 - 2.3.2 Market Analysis of Semiconductor Advanced Packaging in The Middle Atlantic 2013-2017
 - 2.3.3 Market Analysis of Semiconductor Advanced Packaging in The Midwest 2013-2017

- 2.3.4 Market Analysis of Semiconductor Advanced Packaging in The West 2013-2017
- 2.3.5 Market Analysis of Semiconductor Advanced Packaging in The South 2013-2017
- 2.3.6 Market Analysis of Semiconductor Advanced Packaging in Southwest 2013-2017
- 2.4 Market Development Forecast of Semiconductor Advanced Packaging in United States 2018-2023
 - 2.4.1 Market Development Forecast of Semiconductor Advanced Packaging in United States 2018-2023
 - 2.4.2 Market Development Forecast of Semiconductor Advanced Packaging by Regions 2018-2023

CHAPTER 3 UNITED STATES MARKET STATUS AND FORECAST BY TYPES

- 3.1 Whole United States Market Status by Types
 - 3.1.1 Consumption Volume of Semiconductor Advanced Packaging in United States by Types
 - 3.1.2 Revenue of Semiconductor Advanced Packaging in United States by Types
- 3.2 United States Market Status by Types in Major Countries
 - 3.2.1 Market Status by Types in New England
 - 3.2.2 Market Status by Types in The Middle Atlantic
 - 3.2.3 Market Status by Types in The Midwest
 - 3.2.4 Market Status by Types in The West
 - 3.2.5 Market Status by Types in The South
 - 3.2.6 Market Status by Types in Southwest
- 3.3 Market Forecast of Semiconductor Advanced Packaging in United States by Types

CHAPTER 4 UNITED STATES MARKET STATUS AND FORECAST BY DOWNSTREAM INDUSTRY

- 4.1 Demand Volume of Semiconductor Advanced Packaging in United States by Downstream Industry
- 4.2 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in Major Countries
 - 4.2.1 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in New England
 - 4.2.2 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in The Middle Atlantic
 - 4.2.3 Demand Volume of Semiconductor Advanced Packaging by Downstream Industry in The Midwest
 - 4.2.4 Demand Volume of Semiconductor Advanced Packaging by Downstream

Industry in The West

4.2.5 Demand Volume of Semiconductor Advanced Packaging by Downstream

Industry in The South

4.2.6 Demand Volume of Semiconductor Advanced Packaging by Downstream

Industry in Southwest

4.3 Market Forecast of Semiconductor Advanced Packaging in United States by Downstream Industry

CHAPTER 5 MARKET DRIVING FACTOR ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

5.1 United States Economy Situation and Trend Overview

5.2 Semiconductor Advanced Packaging Downstream Industry Situation and Trend Overview

CHAPTER 6 SEMICONDUCTOR ADVANCED PACKAGING MARKET COMPETITION STATUS BY MAJOR PLAYERS IN UNITED STATES

6.1 Sales Volume of Semiconductor Advanced Packaging in United States by Major Players

6.2 Revenue of Semiconductor Advanced Packaging in United States by Major Players

6.3 Basic Information of Semiconductor Advanced Packaging by Major Players

6.3.1 Headquarters Location and Established Time of Semiconductor Advanced Packaging Major Players

6.3.2 Employees and Revenue Level of Semiconductor Advanced Packaging Major Players

6.4 Market Competition News and Trend

6.4.1 Merger, Consolidation or Acquisition News

6.4.2 Investment or Disinvestment News

6.4.3 New Product Development and Launch

CHAPTER 7 SEMICONDUCTOR ADVANCED PACKAGING MAJOR MANUFACTURERS INTRODUCTION AND MARKET DATA

7.1 Advanced Semiconductor Engineering

7.1.1 Company profile

7.1.2 Representative Semiconductor Advanced Packaging Product

7.1.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Advanced Semiconductor Engineering

7.2 Amkor Technology

7.2.1 Company profile

7.2.2 Representative Semiconductor Advanced Packaging Product

7.2.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Amkor Technology

7.3 Samsung Semiconductor

7.3.1 Company profile

7.3.2 Representative Semiconductor Advanced Packaging Product

7.3.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Samsung Semiconductor

7.4 TSMC

7.4.1 Company profile

7.4.2 Representative Semiconductor Advanced Packaging Product

7.4.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of TSMC

7.5 China Wafer Level CSP

7.5.1 Company profile

7.5.2 Representative Semiconductor Advanced Packaging Product

7.5.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of China Wafer Level CSP

7.6 ChipMOS TECHNOLOGIES

7.6.1 Company profile

7.6.2 Representative Semiconductor Advanced Packaging Product

7.6.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of ChipMOS TECHNOLOGIES

7.7 FlipChip International

7.7.1 Company profile

7.7.2 Representative Semiconductor Advanced Packaging Product

7.7.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of FlipChip International

7.8 HANA Micron

7.8.1 Company profile

7.8.2 Representative Semiconductor Advanced Packaging Product

7.8.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of HANA Micron

7.9 Interconnect Systems (Molex)

7.9.1 Company profile

7.9.2 Representative Semiconductor Advanced Packaging Product

7.9.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of

Interconnect Systems (Molex)

7.10 Jiangsu Changjiang Electronics Technology (JCET)

7.10.1 Company profile

7.10.2 Representative Semiconductor Advanced Packaging Product

7.10.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Jiangsu Changjiang Electronics Technology (JCET)

7.11 King Yuan Electronics

7.11.1 Company profile

7.11.2 Representative Semiconductor Advanced Packaging Product

7.11.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of King Yuan Electronics

7.12 Tongfu Microelectronics

7.12.1 Company profile

7.12.2 Representative Semiconductor Advanced Packaging Product

7.12.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Tongfu Microelectronics

7.13 Nepes

7.13.1 Company profile

7.13.2 Representative Semiconductor Advanced Packaging Product

7.13.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Nepes

7.14 Powertech Technology (PTI)

7.14.1 Company profile

7.14.2 Representative Semiconductor Advanced Packaging Product

7.14.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of Powertech Technology (PTI)

7.15 SIGNETICS

7.15.1 Company profile

7.15.2 Representative Semiconductor Advanced Packaging Product

7.15.3 Semiconductor Advanced Packaging Sales, Revenue, Price and Gross Margin of SIGNETICS

7.16 Tianshui Huatian

7.17 Ultratech

7.18 UTAC

CHAPTER 8 UPSTREAM AND DOWNSTREAM MARKET ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

8.1 Industry Chain of Semiconductor Advanced Packaging

8.2 Upstream Market and Representative Companies Analysis

8.3 Downstream Market and Representative Companies Analysis

CHAPTER 9 COST AND GROSS MARGIN ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

9.1 Cost Structure Analysis of Semiconductor Advanced Packaging

9.2 Raw Materials Cost Analysis of Semiconductor Advanced Packaging

9.3 Labor Cost Analysis of Semiconductor Advanced Packaging

9.4 Manufacturing Expenses Analysis of Semiconductor Advanced Packaging

CHAPTER 10 MARKETING STATUS ANALYSIS OF SEMICONDUCTOR ADVANCED PACKAGING

10.1 Marketing Channel

10.1.1 Direct Marketing

10.1.2 Indirect Marketing

10.1.3 Marketing Channel Development Trend

10.2 Market Positioning

10.2.1 Pricing Strategy

10.2.2 Brand Strategy

10.2.3 Target Client

10.3 Distributors/Traders List

CHAPTER 11 REPORT CONCLUSION

CHAPTER 12 RESEARCH METHODOLOGY AND REFERENCE

12.1 Methodology/Research Approach

12.1.1 Research Programs/Design

12.1.2 Market Size Estimation

12.1.3 Market Breakdown and Data Triangulation

12.2 Data Source

12.2.1 Secondary Sources

12.2.2 Primary Sources

12.3 Reference

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